

MANUFACTURING METHOD FOR DEVICE CHIP

ABSTRACT

A manufacturing method for a device chip includes a wafer preparation step of preparing a wafer including a base substrate, a laser beam absorbing layer layered on a front surface of the base substrate, and a device layer being layered on the laser beam absorbing layer and having devices formed in respective separate regions demarcated by a plurality of crossing division lines, a device layer dividing step of forming respective division grooves that divide at least the device layer into individual device chips along the plurality of division lines, and a lift-off step of, after the device layer dividing step is carried out, applying a laser beam of such a wavelength as to be absorbed in the laser beam absorbing layer, from the base substrate side, and lifting off a device chip from the front surface of the base substrate.

[Fig. 3]